MASS TESTING FINAL DESIGN REVIEW Testing methods N. Anfimov. L3 manager



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Dr. Nikolay Anfimov

- photodetectors"
- (China), SiPM R&D.
- Start working at JINR in 2005

WHO AM I



- Ph.D. in Physics and Mathematics "Development and application of methods for studying

- Background in EM-calorimetry for COMPASS-II (CERN), APD and scintillator studying for NOvA (FNAL), 20-inches PMT scanning and testing for JUNO (China), SiPM testing for TAO

- Head of the Sector of Experimental Methods, Experimental Department of Particle Physics, Dzhelepov Laboratory of Nuclear Problems, Joint Institute for Nuclear Research





TAO SIPM

| >TAO physics goals | A |
|--|--------|
| 1. Model-independent reactor neutrino spectrum for | Lev |
| JUNO (with energy resolution $< 3\% / \sqrt{E}$). | (DN |
| 2. A new benchmark to test the nuclear database | Fillin |

Detector scheme

2.8t Gd-LS + 4π SiPM (~10m²) + 3.5t LAB/Silicon Oil (SO) Running at -50 °C, ~30m to core

SiPM Tiles

PDE ~ 50 % Coverage ~95% Size = $5x5 \text{ cm}^2$



HPK Array

4100 tiles

Sub detectors

1. Central detector (CD) Acrylic vessel + Gd-LS SiPM array + copper shell SS tank + LAB/Silicon Oil ACU (from DYB)

2. Veto and shielding LAB exhausting(DN40) and LS filling port(DN20) **HPDE** + **plastic scintillator** Top: Surround: Water tank+ PMT (3") This review addresses SiPM mass-testing 10-cm lead **Bottom:** and SiPM power system

Cryogenic system+ cooling pipes + Heat insulation (PU)







- Requirements and testing methods on SiPM testing. N. Anfimov
- SiPM burn-in testing. P. Hu
- Technical overview on SiPM mass-testing. A. Rybnikov
- SiPM power System. N.Anfimov



SIPM MASS-TESTING **REQUIREMENTS AND METHODS**

- Overview of requirements on SiPMs specifications
- Uniformity of breakdown voltage
- Range of operating voltage -
- Deviation of dark current
- DCR -
- Gain
- PDE deviation from effective PDE
- Crosstalks
- Afterpulses
- ΔPDE
- Summary



OVERVIEW OF REQUIREMENTS **ON SIPMS SPECIFICATIONS**

- Dimensions of Tiles
- 2. Window material
- 3. Defects in the window material (bubbles, pits, etc)
- 4. Cracks and pattern defects on silicon
- 5. Radio purity of Tiles
- 6. Compatibility with LAB
- 7. Type and mounting of connectors

II (d) Burning test

All will be carry out by IHEP group



OVERVIEW OF REQUIREMENTS **ON SIPMS SPECIFICATIONS** (for Mass testing)

- 8. Uniformity of breakdown voltage (Vbd) within 0.19V range
- 9. Range of operating voltage $(V_{op}) > 6.5V$
- 10. Deviation of dark current $@V_{op} \pm 95\%$
- 1. DCR in each channel < 41.7 Hz/mm²
- 12. Gain in each channel $> | \times | 0^6$
- 13. For each channel, $\Delta_{\underline{e}} \ge -25\%$ (PDE_{eff}, PDE, P_{cn})





Good uniformity over

| Tile# | V _{bd} | V _{op} range |
|-------|-----------------|-----------------------|
| | 47.5 | 3.0 ÷ 7.0 |
| 2 | 48.0 - | ► 2.5 ÷ 6.5 ■ |
| 3 | 48.5 | 2.0 ÷ 6.0 |







DEVIATION OF DARK CURRENT [MAX: 95% / TYPICAL: 40% (4St. Dev.) from average value]



10

20

30

40 5 Dark current, nA





40 5 Dark current, nA

20

Direct measurement of dark current by means of Keithley 6487 picoammeter

Accuracy: $\pm (13.2 \div 3.3)\% (3 \div 7V)$







Single oscillogram



DARK COUNT RATE

Run parameters:

| Parameters | Values | Units |
|------------------------|--------|-----------------|
| Time window | 10 | us/oscillogra |
| Number of oscillograms | 30k | - |
| Total acquisition time | 0.3 | second |
| SiPM area | 144 | mm ² |

Expected DCR

| DCR | Rate@-50°C/mm ² | Rate@-50°C/ SiPM | Accura [Istd.d |
|---------|----------------------------|---------------------|-------------------|
| Minimal | 10 cps | 430 cps | ~4.8 |
| Typical | 13.9 cps | 600 cps | ~4.19 |
| Maximal | 41.7 cps | 1800 cps | ~2.4% (+ |

Max probability of pile-ups:

Typical pulse duration: 500 ns Average rate in window (lus): 0.006 [2pulses*500ns*144mm2*41.7cps] Probability of pile-up (2 or more pulses): 0.002%







DARK COUNT RATE [MAX: 41.7 Hz/mm² / TYPICAL: 13.9 Hz/mm²]

ADC data file







(AIN)[MIN: IE6 / TYPICAL: 4E6]

$$GAIN_{pixel} = \frac{P0 - P1}{K_{amp} \cdot q}$$

@ the full length of signals

PO - pedestal position PI - position of the 1st peak Kamp - coeff. of the amplifier q - elementary charge

Accuracy: $\pm (0.42 \div 0.13)\% (3 \div 7V)$









Estimation of the number of photoelectrons





CROSSTALKS [MAX: 15% / TYPICAL: 12%]













Absolute PDE value:

 $PDE_{tao\ sipm} = \frac{\mu_{tao\ sipm}}{\mu_{ref\ sipm}} \times PDE_{ref\ sipm}$

Number of photoelectrons: (µtao sipm, µref sipm) Accuracy: $\pm 0.55\% (3 \div 7V)$

Accuracy depends on calibration of Ref.SiPMs (IHEP team) Accuracy: $\pm 3\%$

SUMMARY

- Method maturity ~100% -
- Equipment maturity ~50%

 - Missing components: mechanics, interface and mother PCBs
- Software maturity ~70%
- Export restrictions from Russia -
 - Partial production in China
- Total cost: ~60k\$ (Onsite) —
- Semi-Clean room, gloves, ESD protection, wearing

- Existing components: PS boards, ADCs, Light system, Current system, Trigger unit

- ADC SW no CLI, PS SW no CANOpen support, Analysis SW no WF analysis



BACKUP SLIDES

AFTERPULSES [MAX: 8% / TYPICAL: 4%]



Outstanding issues:

what is the gate for afterpulse estimation

what is the minimal time to resolve afterpulse signals from the prime pulse

Afterpulse estimation techniques: I. Fast/Total

Integration of waveforms in the long/ short time gates:

-(QLong right - QShort)/QLong right — (QLong left - QShort)/QLong left Estimation of afterpulse probability: $P_{afterpulse} = P_{N0} - P_{D0}$ where: $P_{N0} = N_0/Entries$, $P_{D0} = D_0/Entries$

2. Fitting of waveforms

- requires computing power
- offline analisys
- is not resolved within 100-200 ns



AFTERPULSES

